

PCN Notification Date: 08/31/2020

Final PCN

Lead Frame Supplier Source change to support the 40 VQFN component material

Dear Customer.

We are pleased to announce the successful completion of the qualification for the Lead Frame Supplier SH Electronics Suzhou Co., Ltd (Jiangsu Suzhou CHINA) an affiliate of Chang Wah Technology Co., Ltd. to support the 40 VQFN component material.

This document serves as the Final PCN notification for the use and migration to the 40 VQFN Lead Frame Supplier SH Electronics Suzhou Co., Ltd (Jiangsu Suzhou CHINA) an affiliate of Chang Wah Technology Co., Ltd. This described change is effective immediately based on the successful completion of the qualification to ensure continuity of supply without disruption.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Quality Systems Administrator Cirrus Logic Corporate Quality Phone: +1(512) 851-4000



CIRRUS LOGIC[®] Process Change Notification

PCN Number: PCN-2020-131

PCN Notification Date: 08/31/2020

Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:		Lead Frame Supplier Source change to support the 40 VQFN component material							
Cus	Customer Contact: Local Field Sa			s Representative Phone: (512) 851-			Dept:	Corporate Quality	
Pro	Proposed 1 st Ship Date:			ugust 2020 Estimated Sample Av			ilability Date: July 2020		
	Assembly Site			Assembly Process			Assembly Materials		
	Wafer Fab Site			Wafer Fab Process			Wafer Fab Materials		
	Wafer Bump Site			Wafer Bump Process			Wafer Bump Material		
	Test Site			Test Process			Design		
	Electrical Specification		Х	Mechanica	Mechanical Specification		Part Number		
	Packing/Shipping/Labeling		Х	Other			Data Sheet		
Con	Comments: Lead Frame Mat		erial \$	Supplier					

PCN Details

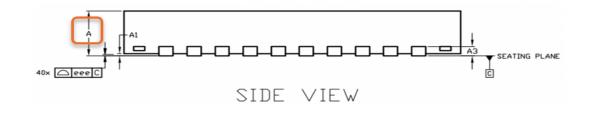
Description of Change:

• Lead Frame Supplier:

- From: Dynacraft Industries Sdn. Bhd. (Penang, Malaysia)
- To: SH Electronics Suzhou Co., Ltd (Jiangsu Suzhou CHINA) an affiliate of Chang Wah Technology Co., Ltd.
 - Note: SH Electronics Suzhou Co., Ltd. is a qualified lead frame supplier
- Lead Frame POD (Package Outline Drawing) Dimension(s): (Reference Appendix A: Dimensional Comparison Drawing)

			CURRENT		NEW			
	Dim	Min	Nom	Max	Min	Nom	Max	
Pkg Height	Α	0.85	0.90	0.95	0.80	0.85	0.90	
Note DOD Developed of the ULEDEO Official Detriction and the								

Note: POD Remains Consistent with JEDEC Standard. Data sheet update not required.



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 All other POD (Package Outline Drawing) Dimensions Remain the same: Reference Appendix A Lead Frame Material: Remains the same: C194 Mold Compound Material: Remains the same: Hitachi CEL 9240 DIE Attach Material: Remains the same: Ablebond 8290 Moisture Sensitivity Level (MSL): Remains the same: MSL 3 Reason for Change: Maintain continuity of material supply. Anticipated Impact on Form, Fit, Function, Quality or Reliability: No anticipated adverse impact to the quality and/or reliability of said product. Anticipated Impact on Material Declaration: Image: Material Declaration <	Special Note: Items Remaining the Same									
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2 CS42L52-CNZR 3 CS43L22-CNZ										
3 CS43L22-CNZ										

Changes To Product Identification Resulting From This PCN:

There are no changes to the production identification



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The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

Qualification Plan

Reliability Test	Standard	Standard Conditions	
Pre-Conditioning	JEDEC J-STD-020A	MSL3 / 260°C (1 Lots)	22 / 0
Die Shear Strength	MIL-STD-883 METHOD 2019		40 / 0
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (# Lots)	40 / 0
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (# Lots)	40 / 0
Plating Thickness		40 Units (10 units / Block)	40 / 0
SD (Solderability)	JESD22 B102	245°C / 8 hr steam age before SD (1 Lots)	15 / 0
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lots)	40 / 0

Notes:

- Qualification tests "pass" on zero fails for each test •
- CS42L52-CNZ serves as the Qualification Vehicle for the 40 VQFN Lead Frame Material •

Reliability Qualification Results:

The material has met all qualification requirements and is fit for use •



Before: MBOL

> A A1 A3 b D Ε D2 E2 e L к ۵۵۵ bbb CCC ddd eee fff

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APPENDIX A – POD (PACKAGE OUTLINE DRAWING) COMPARISON

					CDATU	M A DR ID				
					777@ICI48	-32	R0.125			
					the	Int				
					J CI L	THE P				
× /	MIN.	NDM.	MAX.		EVEN/DDD DETA	TERMINAL SIDE	KINAL TIP			
	0.70	0.75	0.80		DETH	12 D				
	0.85	0.90	0.95							
	0	0.02	0.05		After:					
	_	0.20 REF	-			MIN. NDM.	MAX.			
	0.20	0.25	0.30		A	0.70 0.75	0.80			
-	0.20	6.00BSC	0.00		A1	0.02	0.90			
-					ETAIL A A3	- 0.20 RE				
		6.00BSC		BOTTOM VIEW BOTTOM VIEW	k	0.20 0.25	0.30			
	4.00	4.10	4.20		D	6.00BS0				
	4.00	4.10	4.20		DS	4.00 4.10	4.20			
-	1.00	0.50BSC	1120		E2	4.00 4.10	4.20			
-					e	0.50BS0				
	0.40	0.45	0.50	SIDE VIEW	L K	0.40 0.45	0.50			
	0.20	-		EVEN/DDD TERMINAL SIDE	000	0.20 -				
-	0.000	0.15		DETAIL A	lololo	0.10				
_					ccc	0.10				
		0.10		NUTES	lololo	0.05				
0.10				1. DIMENSIONING AND TOLERANCING CONFIRM TO ASME Y14.5M-1994	eee	0.08				
-				2. ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES ARE IN DEGREE.		0.10				
0.05				3 UNIL ATERAL CONTACT APPLIES TO THE EXPOSED HEAT SINK SLUG AS THE TERMAN IS AND THE RADIA AND THE REAL AND T						
0.08				4. SIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.150mm TO 0.30mm FROM THE (6*6PKG)						
0.10				TERMINAL TIP. DIMENSION & SHOULE NOT BE MEASURED IN RADIUS AREA.	IONALS ANGLES DRAWING	IC NO	REY.			
				5. ALL SPEC TAKE JEDEC MD-220 FOR REFERENCE.	RECTON SCALE SZE Moteri	ar S-PED-PKFN040-06-01 AA sez A4 Moterial Code. 2004026554 SetET A4 Reference Code. MD-220 2 OF 2				